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(54) Title: **HEAT RELEASABLE WAFER DICING TAPE**

(57) Abstract: A thermocurable pressure sensitive adhesive composition is provided comprised of at least one pressure sensitive adhesive, at least one multifunctional monomer or oligomer, at least one free radical initiator, and optionally a crosslinking agent. The pressure sensitive adhesive composition of the present invention may be used with advantage in the production of a semiconductor chip, wherein a wafer chip is attached to the pressure sensitive adhesive layer during the chip manufacturing process during which a diced chip is produced. The adhesive composition may be thermocured once the diced chip has been processed to permit ease of removal of the diced chip due to loss of adhesion by the adhesive composition as a result of being thermocured.

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